## Remarks

Reconsideration of this patent application is respectfully requested, particularly as herein amended.

Following a summary of the status of this Patent Application, the Office Action of July 7, 2009, rejects claims 14 to 25 and 32 to 35 under 35 U.S.C. §112, first paragraph, for allegedly failing to comply with the enablement requirement.

Claims 14 to 25 are rejected because claim 14 recites
"an isolating circuit coupled with the fluid transport circuit",
and the position is taken that this "limitation is not described
in the Specification of the Instant Application". This position
is respectfully traversed in view of the disclosure provided in
Figures 11 and 12 of the originally submitted drawings and from
line 18 of page 13 through line 13 of page 14 of the English
translation of the French text specification which was originally
submitted when entering the national phase of the International
Application on which the current U.S. Patent Application is based.

The referenced disclosure describes a fluid circulation layer 15 which is implemented as a follower layer, and isolating follower channels 23 (Figure 11) or an isolating follower layer 24 (Figure 12) which "are located at a constant or variable distance from the regulating follower layer (15)". The channels 23 and the layer 24 are provided "in order to limit the thermal conduction toward the sides... and/or toward the bottom... of

the mold..." and "form either an active isolation or secondary regulation, or a passive isolation" of the follower layer 15.

It is respectfully submitted that one skilled in the art to which this subject matter pertains would have understood this to constitute a coupling of the layer 15 with either the channels 23 or the layer 24, enabling one skilled in the art to which this subject matter pertains to make and/or use the invention as was previously recited in claim 14, and as is now recited in claims 13 and 15. Further support for this position is available with reference to page 338 of "Webster's New World Dictionary", a copy of which is submitted with this Reply. Reference is made to the first definition listed for the word "coupling", which is "a joining together; pairing", and the second definition for the word "couple", which is "two things of the same sort that are joined together or associated; pair". Reconsideration and withdrawal of the stated rejection of claims is, therefore, respectfully requested.

Claims 32 to 35 are rejected because claim 32 recites
"a thermal barrier between the fluid transport circuit and the
body of the part", and the position is again taken that this
"limitation is not described in the Specification of the Instant
Application". It is respectfully submitted that such structure
was again described in the disclosure provided in Figures 11 and
12 of the originally submitted drawings and from line 18 of page
13 to line 13 of page 14 of the English translation of the French

text specification which was originally submitted when entering the national phase of the International Application on which the current U.S. Patent Application is based. Nevertheless, and in an effort to advance the prosecution of this Patent Application, the language of claim 32 has been amended to more closely follow the language originally presented in applicants' disclosure. It is respectfully submitted that this leaves most the rejection of claims 32 to 35 under 35 U.S.C. §112, first paragraph, and reconsideration and withdrawal of this rejection of claims is respectfully requested.

The Office Action of July 7, 2009, next rejects claims 21 and 22 under 35 U.S.C. §112, second paragraph, as indefinite for reasons stated in the Office Action. Claim 13 has presently been amended to incorporate the subject matter of former claim 14, claim 15 has been amended to incorporate the subject matter of former claim 20 (claims 14 and 20 have been canceled), and claims 21 and 22 have been amended to depend from claim 15. It is respectfully submitted that this leaves moot the rejection of claims 32 to 35 under 35 U.S.C. §112, second paragraph, and reconsideration and withdrawal of this rejection of claims is respectfully requested.

The Office Action of July 7, 2009, next rejects claims 13 to 17, 20 to 24 and 26 to 31 under 35 U.S.C. §103(a) as being unpatentable over a proposed combination of the previously cited article authored by Choi et al. with U.S. Patent No. 5,847,958

(Shaikh et al.). Claims 18, 19, 25 and 32 to 35 are rejected over the proposed combination of Choi et al. and Shaikh et al., in further proposed combination with the previously cited patent of Sachs et al. (U.S. Patent No. 5,775,402).

As has previously been indicated, claim 13 has been amended to incorporate the subject matter of former claim 14. Further noted, however, is the italicized text that connects pages 6 and 7 of the Office Action of July 7, 2009, indicating that "the term 'isolating circuit' and 'fluid transport circuit' are being considered as referring to the same circuit" because former claim 14 was not considered to comply with the enablement requirement of 35 U.S.C. §112, first paragraph. It is submitted that, for reasons previously discussed, it has been shown that the subject matter of claim 14 was in full compliance with the enablement requirement of 35 U.S.C. §112, first paragraph, and that the "isolating circuit" and the "fluid transport circuit" recited in claim 14 were not properly "considered as referring to the same circuit". It is, therefore, respectfully submitted that this leaves moot the rejections of claims under 35 U.S.C. §103(a) in view of the proposed combinations of Choi et al., Shaikh et al. and Sachs et al. which are presented in the Office Action of July 7, 2009. Because such subject matter is currently recited in independent claim 13, a reconsideration of all pending claims is respectfully requested.

It is further submitted that the above-discussed

amendments to the claims operate to even more clearly identify significant and patentable distinctions present in applicants' claims, including the following.

Applicants' claims 13 and 15 are generally directed to a mold produced by computer-aided design which breaks down the body of the mold into elementary strata, followed by manufacture of the elementary strata and assembly of the manufactured strata to reconstruct the mold. As part of this, a fluid transport circuit and an isolating circuit are developed within the mold. The fluid transport circuit is broken down into a plurality of elementary chambers, which are produced in the manufactured strata during their manufacture, for reconstruction of the fluid transport circuit upon assembly of the manufactured strata. isolating circuit is broken down into a plurality of elementary isolating chambers, which are also produced in the manufactured strata during their manufacture, for reconstruction of the isolating circuit upon assembly of the manufactured strata. Also related to this are newly presented claims 36 and 37, which are further directed to production of the elementary chambers and the elementary isolating chambers during the manufacture of the manufactured strata, including simultaneous production of the elementary chambers and elementary isolating Support for these features is provided in the original specification for this Patent Application, from line 25 to line 29 of page 13, and with reference to Figures 11 and 12 of the

originally submitted drawings.

Choi et al. disclose various methods for performing a computer-aided manufacture of structures from laminated sheets, including the method of "Stratoconception" that was identified in the specification for this Patent Application (e.g., at line 10 of page 4 of the original specification), and the disclosed methods have certain features in common with elements recited in applicants' claims. However, there are also significant differences between applicants' claims and the disclosure of Choi et al.

Some of these differences, pertaining to the recited fluid transport circuit, are noted at the middle of page 5 of the Office Action of July 7, 2009. Other differences, pertaining to the recited isolating circuit, are not specifically acknowledged in the Office Action. It is noted, however, that the patent to Shaikh et al. is cited for purposes of rejecting claims directed to the isolating circuit, and not the article of Choi et al. It is, therefore, respectfully submitted that Choi et al. also fail to disclose the isolating circuit recited in applicants' claims.

Shaikh et al. has been cited as a disclosure of the various elements recited in applicants' claims which are absent from the disclosure of Choi et al. It is submitted, however, that in view of the foregoing discussion, it becomes clear that Shaikh et al. do not, in fact, disclose the subject matter which is recited in applicants' claims, and reconsideration of the

patentability of applicants' claims is respectfully requested in view of the following.

As is noted in the Office Action, Shaikh et al. also disclose rapid prototyping methods including the machining of a plurality of thick stratiform members, in the nature of "slabs" (see, for example, lines 5 to 11 of column 3), and the disclosed methods have certain features in common with elements recited in applicants' claims resulting from the common features of a rapid prototyping process. However, Shaikh et al. do not disclose the manufacture of a mold having a fluid transport circuit which is coupled with an isolating circuit, in accordance with applicants' claims, or otherwise, or how such a mold is to be configured.

Although not cited in connection with applicants' claims 13 to 17, 20 to 24 and 26 to 31, the disclosure of Sachs et al. also fails to disclose a mold produced by computer-aided design which breaks down the body of the mold into elementary strata, followed by manufacture of the elementary strata and assembly of the manufactured strata to reconstruct the mold, and having a fluid transport circuit which is coupled with an isolating circuit, either in accordance with applicants' claims, or otherwise.

As a consequence, it is respectfully submitted that applicants' claims are directed to a method and a mold formed by such a method having features which are significantly and patentably different from the processes and parts disclosed by

Choi et al., Shaikh et al. and Sachs et al. Applicants' claims are further directed to the following distinguishing features, as well.

Claims 16, 17 and 27 to 29 are directed to the fluid transport circuit which is developed following reconstruction of the manufactured strata, including a fluid transport circuit which is capable of forming the three-dimensional network of channels shown in Figure 1 of the drawings (claims 16 and 28) and the layer-shaped chamber shown in Figure 5 of the drawings (claims 17 and 29). In accordance with the present invention, effective heat transfer is achieved with a fluid transport circuit formed either as a three-dimensional network or as a layer-shaped chamber, so that the mold always has an optimized thickness between the channels or the chamber and the surface of the mold. This is not disclosed by Choi et al., Shaikh et al. or Sachs et al.

Claim 19 is directed to a fluid transport circuit, interior portions of which have a plurality of transverse fins for mechanically reinforcing the fluid transport circuit and for stirring the circulated fluid. No such structure is disclosed by Choi et al. or Shaikh et al., and the fins 11, mounds 12, 14 and stubs 13 disclosed by Sachs et al. do not provide mechanical reinforcement of the channels which incorporate them. As a consequence, such structure is not disclosed by Choi et al., Shaikh et al. or Sachs et al.

Claims 21, 22 and 32 to 35 are directed to the isolating circuit which is coupled with the fluid transport circuit and which is also developed following reconstruction of the manufactured strata, including an isolating circuit which is capable of forming a three-dimensional network of channels and an isolating circuit which is formed as a layer-shaped chamber. accordance with the present invention, problems such as excessive thermal inertia of the molds and the uncontrollable influence of external conditions on regulation of the manufactured molds are overcome by combining the fluid transport circuit with an isolating circuit in the form of a three-dimensional network of channels or a layer-shaped chamber, which can be filled by an insulating material, by air, or by a suitable heat transfer fluid. No such structure is disclosed by Choi et al., Shaikh et al. or Sachs et al. Also related to this are the adhesives recited in claim 23, which combine to provide the assembly of manufactured strata with appropriate mechanical properties while maintaining appropriate thermal conductivity through the resulting structure.

Claims 30 and 31 are directed to production of the manufactured strata, reciting formation of the elementary chambers in surface portions of the manufactured strata, to a depth less than the defined thickness of the manufactured strata, and combination of the elementary chambers with the surface portions of adjacent manufactured strata to form the fluid

transport circuit. Such features are not disclosed by Choi et al., Shaikh et al. or Sachs et al.

It is, therefore, respectfully submitted that applicants' claims are not subject to rejection under 35 U.S.C. \$103(a) based on the disclosures of Choi et al., Shaikh et al. and Sachs et al., and that applicants' claims are in condition for allowance.

Corresponding action is earnestly solicited.

Respectfully submitted,

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territory: 2. in English history, formorly, a count or earl with supreme power in his country.

country field (furn'th-field'), adi. (country + fy, + ed).

1. rural; rustic. 2. having the appearance, actions, etc. attributed to country people. Also spelled country field. (country field (furn'th-field'), adi. (country field, field).

country (kuntrh). In [b]. country in [country field. country field field field field. country field field field field field field field field. country field f

county palatine, the land hald by a count palatine.
county palatine, the land hald by a count palatine.
county seat, a town or city that is the center of a county
government.
coup (koo), n. [pl. coups (koo); Fr. koo)], [Fr., LL.
\*\*colpus, colapus, L. colapus, a cuff. box on the ear; Cr.
\*\*kolapus, olapus, L. colapus, a cuff. box on the ear; Cr.
\*\*kolapus, 1. literally, a blow. 2. a sudden, successful
move or action; brilliant stroke; clever stratagem,
teoup de grace (koo) de grace), [Fr., lit., stroke of
mercy], 1. the blow, shot, etc. that brings death to a
sufferer; death blow; bettee. 2. a finishing stroke.
teoup de main (koo) de man'), [Fr., lit., stroke of
hand, a surprise attack or movement, as in war.
teoup d'é-tra (koo) da 'ta'), [Fr., lit., stroke of state], a
sudden, forceful stroke in politics; especially, the sudden, forcible overthrow of a government.
teoup de thé-à-tre (koo) da 'ta'), [Fr., lit., stroke of theater]. 1. a surprising or startling turn in a drama.
2. an action for sensational effect; theatrical action,
teoup d'slance; quick view or survey.
coupe (koo); orig, but now less often, koo-pa'), n. [see
oupe (koo-pa'), n. [Fr., pp. of couper, to cut], 1. a
closed carriage seasing
two passengers, with a
seat outside for the
driver. 2 in Buropean
railway cars, a half-compartment at the cud,
with seats on only one
side. 3. a coupe: now
the less common form of
the word.
Coupe-rim, Fran-cole

Con perin, Francois



(Itin'swa' ko'pran'), 1668-1733; Fronch composer. Con-perus, Lou-is (155-1733; Lou-is (1



same length that rhymo. 2. [Ranol, a couple; pair.
coupling (kup'lin), n. [see
torether; pairing. 2. a
mechanical dovice for joining parts together. 3. a
device for joining two railroad cars together. 4. the
part of the body of a dog,
horse, etc. between the
forequarters and hindquarters and hindquarters and bindquarters. 5. a method of
duvice for joining two railror of energy from one to the other.

COB-pon (k60'pon, k6'pon), n. [Fr., remnant, coupon <
cospor, to cut). 1. a detachable printed statement on a
bond, specifying the interest due; the holder can present
it for payment at the proper time. 2. a part of a ticket
or a certificate given with packaged goods, entitling the
buyer to a specified right, as an ontertainment, redemption for cash or gifts, etc. 3. a part of a printed advertimement that can be used to order goods, samples, etc.
courrage (kulr'in). n. [MB., corage; Off., corage, curage,
heart, spirit < L. cor. heart). I, the artitude or response
of facing and dealing with anything recognized as
dangerous, difficult, or painful, instead of withdrawing
from it; quality of being fessiless of brave; valor; pluck.
2. [Oba], mind; purpose; disposition; spirit; temper,
the courage of one's convictions, the courage to do
what one thinks is right.

Courage (kcoriant), n. covirante.
courante (kco-fant', fr. k60'fant'), n. [fr. < courant,
ppr. of courie to run glide; L. currers, to run]. I an
old, lively French dance with gliding or running stops.
2. the music for this dance.

Courbet, Gus-tave (gus-tav) koorbe'), 1819-1877;
French painter.

Courier (koori-5r, kcir'i-6), n. [ME. cover (Off.
currer, LL. curriur); also ME. courie. (Off. currers
courier (koori-6r, kcir'i-6), n. [ME. cover (Off.
currer, to run; also fr. course, to run]. 1. a messanper, neally one sont in hacte with important or urgent
take care of hocke accompany travelers and
take care of hocke accom

cour

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